



Final Product Change Notification

202106030F01 : MC33771B Product Burn-In Elimination On Improved Quality Robustness Silicon Design

Note: This notice is NXP Company Proprietary.

Issue Date: Jul 09, 2021 **Effective date:** Oct 07, 2021



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For detailed information we invite you to [view this notification online](#)

Management summary

Burn-in Elimination from the Final Test production flow for the BCC14 Rev B+ MC33771B products.

Change Category

- | | | | | |
|--|---|--|--|---|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input checked="" type="checkbox"/> Test Process | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Location | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware <input type="checkbox"/> Other | | | | |

PCN Overview

Description

NXP Semiconductors announces the Burn-in elimination from the Final Test production flow for the MC33771B Battery Cell Controller IC products associated with this notification. As previously informed with notification 202008032IU01 (Sep 2020), MC33771B product was migrated to an improved quality robustness design. The burn-in process was originally introduced on MC33771B product to address qualification rejects linked to PMV5 capacitors. The PMV5 capacitors were removed from MC33771B with the enhanced quality design migration.

In order to confirm efficiency of the new design, NXP performed a burn-in study. The burn-in elimination evaluation was successfully completed after testing 100k units from 5 different wafer lots and 12 assembly lots, processed in the same wafer fabrication facility, with zero burn-in related failures.

Upon PCN 202106030F01 approval, the burn-in process will be removed from the Final Test production flow for improved quality design MC33771B products.

Please see the attached files for additional details.

Corresponding ZVEI Delta Qualification Matrix ID: SEM-QG-01

Reason

The original reason for burn-in implementation (qualification rejects linked to PMV5 capacitors), has been resolved with product migration to improved quality design.

Burn-in elimination can now proceed, and results in optimized manufacturing test flow for reduced cycle time and enhanced product delivery.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Not Applicable

Production

Planned first shipment Oct 07, 2021

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Self qualification: [view online](#)

Additional documents: [view online](#)

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Aug 08, 2021.

Related Notification

Notification	Issue Date	Effective Date	Title
202008032IU01	Sep 20, 2020	Sep 21, 2020	MC33771B Design Quality Robustness Improvement Update Notification

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Antoine Storez
Position Quality Engineer
e-mail address antoine.storez@nxp.com

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NXP Quality Management Team.

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NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands

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